

OT2-SN63-T4

Rev: 15.2

| | |
|----------|------------|
| Date | 2021.06.28 |
| Language | English |
| SDS | 950707 |



SUMMARY

SnPb - Premium latest technology No-Clean, Fine Pitch solder paste - Halide/Halogen free

| PASTE | OT2-SN63-T4 |
|----------------------|-------------|
| PROCESS | |
| No-Clean process | 9 |
| Post-solder cleaning | 9 |

| INDUSTRY APPLICATION | |
|---------------------------------|---|
| Standard electronics | 9 |
| Industrial electronics | 9 |
| Hi-Rel electronics (automotive) | 9 |

| PROCESS CAPABILITY | |
|----------------------------|-----|
| Squeegee | 9 |
| ProFlow | TBD |
| Pb-free Profile Air, short | 9 |
| Pb-free Profile Air, long | 9 |
| Pb-free process N2 | 9 |
| Vapor phase process | 7 |
| Shiny joint appearance | 9 |
| Cosmetic cleanliness | 9 |
| ICCT compatible | 9 |
| Conformal coating | 8 |

| Legend | |
|--|--------|
| <i>Especially made for this purpose</i> | 9 - 10 |
| <i>Generally qualified for this purpose</i> | 7 - 8 |
| <i>Generally usable, but not the best choice</i> | 5 - 6 |
| <i>Generally not usable for this purpose</i> | 3 - 4 |
| <i>Wrong choice</i> | 1 - 2 |

Check material compatibility with every process change!

Industrial chemical product.

Read MSDS before use.

Product contains SVHC substance Lead with more than 0,1 Mass%.

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| CLASSIFICATION | |
|------------------------------|------------|
| DIN-EN-29454-1: 1994 | 1.1.3.C |
| IPC-J-STD-004-A: 2004 | ROL0 |
| IPC-J-STD-005: 1995 (Powder) | T4 |
| Particle size | [µm] 20-38 |

| PROPERTIES | | |
|------------------------|------------|--------------|
| Flux code | OT2 | |
| Alloy Code | SN63 | |
| Alloy composition | Sn63Pb37 | |
| Liquidus | [°C] | 183 |
| Solidus | [°C] | 183 |
| Recommended peak temp. | [°C] | 205-225 |
| Acid number | [mg KOH/g] | 142.9 |
| Flux | [% w/w] | 11 |
| Residues | Colorless | |
| Tackiness Malcom TK1 | JIS-Z-3284 | [gf] @ 0h 90 |

| TEST REPORTS | | | |
|---------------------------|---------------------|--------------------|-----------|
| IPC/ANSI-J-STD-005 | | | Compliant |
| Certificate of Compliance | | | Website |
| RoHS Compliant | | | No |
| Application Note | | | EN/DE |
| Copper Mirror | IPC-TM-650 2.3.32 | | Pass |
| Halides | IPC-TM-650 2.3.33 | [Silver Chromate] | Pass |
| Halide | IPC-TM-650 2.3.35.1 | [Fluoride by Spot] | Pass |
| Copper Corrosion | IPC-TM-650 2.6.15 | | Pass |
| SIR | IPC-TM-650 2.6.3.3 | | Pass |
| ECM | IPC-TM-650 2.6.14.1 | | Pass |

| PACKAGING AND STORAGE | | |
|------------------------------|----------|------|
| Packaging jar | PP [g] | 500 |
| Packaging cartridge | HDPE [g] | 650 |
| Packaging cartridge | HDPE [g] | 1300 |
| Packaging Cassette Pro-Flow | [g] | 800 |
| Minimum shelf-life in months | 4-10 °C | 5 |